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FDP6030L/FDB6030L

N-Channel Logic Level PowerTrench® MOSFET

General Description

This N-Channel Logic Level MOSFET has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers.

These MOSFETs feature faster switching and lower gate charge than other MOSFETs with comparable $R_{\text{DS(ON)}}\text{specifications}.$

The result is a MOSFET that is easy and safer to drive (even at very high frequencies), and DC/DC power supply designs with higher overall efficiency.

It has been optimized for low gate charge, low $R_{\text{DS}(\text{ON})}$ and fast switching speed.

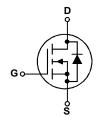
Features

- 48 A, 30 V $R_{DS(ON)} = 13 \text{ m}\Omega$ @ $V_{GS} = 10 \text{ V}$ $R_{DS(ON)} = 17 \text{ m}\Omega$ @ $V_{GS} = 4.5 \text{ V}$
- Critical DC electrical parameters specified at elevated temperature
- High performance trench technology for extremely low $R_{\mbox{\scriptsize DS}(\mbox{\scriptsize ON})}$
- 175°C maximum junction temperature rating





D



TO-220 S TO-263AB
FDP Series FDB Series

Absolute Maximum Ratings T_A=25°C unless otherwise noted

Symbol	Parameter	Ratings	
V _{DSS}	Drain-Source Voltage	30	V
V _{GSS}	Gate-Source Voltage	± 20	V
I _D	Drain Current - Continuous (Note 1)	48	Α
	- Pulsed	150	
P _D	Total Power Dissipation @ T _C = 25°C	52	W
	Derate above 25°C	0.3	W/°C
T _J , T _{STG}	Operating and Storage Junction Temperature Range	-65 to +175	°C

Thermal Characteristics

$R_{ heta JC}$	Thermal Resistance, Junction-to-Case	2.9	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62.5	

Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape width	Quantity
FDB6030L	FDB6030L	13"	24mm	800 units
FDP6030L	FDP6030L	Tube	n/a	45

Symbol	Parameter	stics T _A = 25°C unless otherwise noted eter Test Conditions		Тур	Max	Units
Symbol	Farameter	rest conditions	Min	тур	IVIAX	Ullits
	purce Avalanche Ratings (Note		1			
E _{AS}	Single Pulse Drain-Source Avalanche Energy	$V_{DD} = 15 \text{ V}, \qquad I_D = 26 \text{ A}$			100	mJ
I _{AS}	Maximum Drain-Source Avalanche Current				26	Α
Off Char	acteristics	•	•			
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, \qquad I_{D} = 250 \mu\text{A}$	30			V
ΔBV _{DSS} ΔT _J	Breakdown Voltage Temperature Coefficient	I_D = 250 μ A, Referenced to 25°C		23		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 24 V, V _{GS} = 0 V			1	μΑ
I _{GSS}	Gate–Body Leakage	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			± 100	nA
On Char	acteristics (Note 2)					
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$, $I_{D} = 250 \mu A$	1	1.9	3	V
$\Delta V_{GS(th)} \over \Delta T_J$	Gate Threshold Voltage Temperature Coefficient	I_D = 250 μA, Referenced to 25°C		- 5		mV/°C
R _{DS(on)}	Static Drain–Source On– Resistance	$V_{GS} = 10 \text{ V}, \qquad I_D = 26 \text{ A}$ $V_{GS} = 4.5 \text{ V}, \qquad I_D = 21 \text{ A}$ $V_{GS} = 10 \text{ V}, I_D = 26 \text{ A}, T_J = 125^{\circ}\text{C}$		7.9 10.2 13.0	13 17 20	mΩ
I _{D(on)}	On-State Drain Current	V _{GS} = 10 V, V _{DS} = 10 V	60			Α
g _{FS}	Forward Transconductance	V _{DS} = 10V, I _D = 26 A		68		S
-	Characteristics	<u> </u>	1			
C _{iss}	Input Capacitance	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V},$		1250		pF
Coss	Output Capacitance	f = 1.0 MHz		330		pF
C _{rss}	Reverse Transfer Capacitance	1		155		pF
R _G	Gate Resistance	V _{GS} = 15 mV, f = 1.0 MHz		1.3		Ω
Switchin	g Characteristics (Note 2)		•	•		
t _{d(on)}	Turn-On Delay Time	$V_{DD} = 15V$, $I_{D} = 1 A$,		11	20	ns
tr	Turn-On Rise Time	$V_{GS} = 10 \text{ V}, \qquad R_{GEN} = 6 \Omega$		12	22	ns
t _{d(off)}	Turn-Off Delay Time	1		29	46	ns
t _f	Turn-Off Fall Time	1		12	21	ns
Qg	Total Gate Charge	$V_{DS} = 15 \text{ V}, \qquad I_{D} = 26 \text{ A},$		13	18	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 5 V		3.9		nC
Q_{gd}	Gate-Drain Charge			5.2		nC
Drain-Se	ource Diode Characteristics	and Maximum Ratings				
Is	Maximum Continuous Drain–Source	<u> </u>			48	Α
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 26 A (Note 1)		0.92	1.3	V
t _{rr}	Diode Reverse Recovery Time	I _F = 26 A,		26		nS
Q _{rr}	Diode Reverse Recovery Charge	$d_{iF}/d_{t} = 100 \text{ A/}\mu\text{s}$		15		nC

Notes

- 1. Calculated continuous current based on maximum allowable junction temperature.
- 2. Pulse Test: Pulse Width < 300μs, Duty Cycle < 2.0%

Typical Characteristics

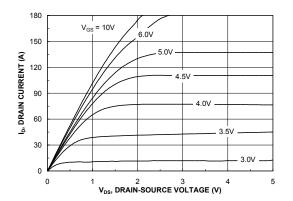


Figure 1. On-Region Characteristics.

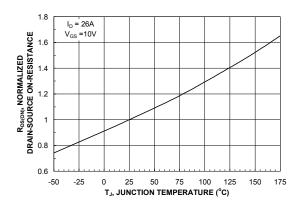


Figure 3. On-Resistance Variation with Temperature.

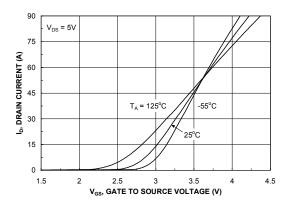


Figure 5. Transfer Characteristics.

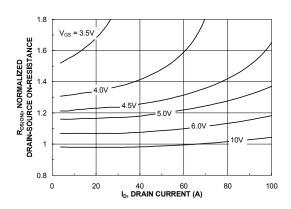


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

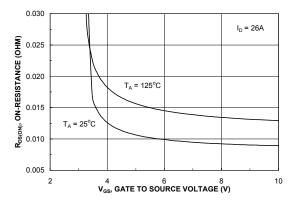


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

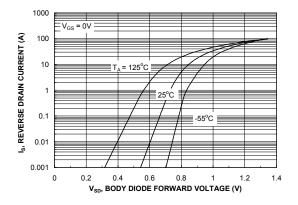
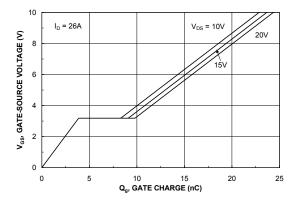


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics



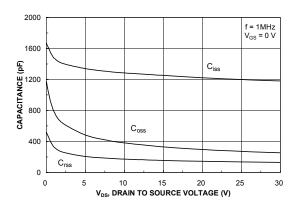
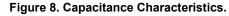
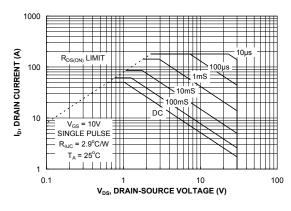


Figure 7. Gate Charge Characteristics.





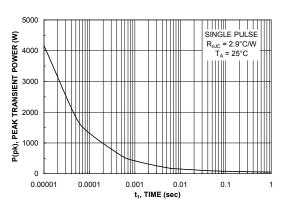


Figure 9. Maximum Safe Operating Area.

Figure 10. Single Pulse Maximum Power Dissipation.

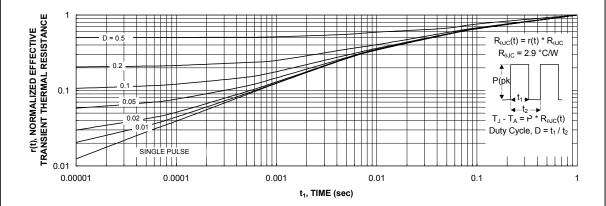


Figure 11. Transient Thermal Response Curve

Thermal characterization performed using the conditions described in Note 1b. Transient thermal response will change depending on the circuit board design.

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SuperSOT™-3

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